

	Title	Current OR
1	Method of manufacturing a multilayer circuit board	29/830
2	Method of installing fasteners into a panel using a self-adjusting fastener installation head	29/407.05
3	Two-sided printed circuit board a multi-layered printed circuit board	174/265
4	Electrical interconnections between adjacent circuit board layers of a multi-layer circuit board	174/264
5	Method of manufacturing a multilayer circuit board	29/830
6	Multi-layer circuit construction methods with customization features	29/830
7	Process of making interconnection structure for semiconductor device	29/832
8	METHODS OF FORMING CIRCUIT INTERCONNECTIONS	29/843

	Title	Current OR
9	CIRCUITRY AND METHOD	29/830
10	METHOD FOR CONNECTING CONDUCTORS	29/830

	Current XRef
1	228/175; 29/739; 29/848; 361/792; 428/422
2	29/432
3	174/261; 174/262
4	174/262; 174/263; 257/E23.172; 361/778; 361/795
5	174/262; 174/263; 428/901
6	257/E23.173; 29/846; 29/852; 427/97
7	174/258; 174/259
8	174/263; 228/180.21; 228/187; 228/188; 228/189; 228/190; 228/195; 228/228; 228/254; 228/262; 29/830; 361/779; 361/792

	Current XRef
9	174/253; 174/254; 174/257; 174/261; 216/18; 257/700; 257/E21.511; 257/E23.055; 257/E23.065; 257/E23.174; 29/832; 29/840; 29/852; 361/751; 438/125
10	156/150; 156/151; 228/175; 228/180.21; 228/230; 29/843